

Features

- P-Channel, -5V Logic Level Control
- Low on-resistance RDS(on) @ V_{GS}=-4.5 V
- Fast Switching
- Enhancement mode
- 100% Avalanche Tested
- Pb-free lead plating; RoHS compliant

V_{DS}	-30	V
$R_{DS(on),TYP} @ V_{GS}=-10\text{ V}$	8.8	$\text{m}\Omega$
$R_{DS(on),TYP} @ V_{GS}=-4.5\text{ V}$	16	$\text{m}\Omega$
I_D	-50	A

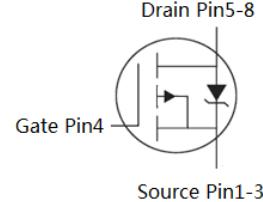
PDFN5x6



Pin1



Part ID	Package Type	Marking	Tape and reel information
VS3508AP	PDFN5x6	3508AP	3000pcs/reel



Source Pin1-3

Maximum ratings, at $T_j=25\text{ }^\circ\text{C}$, unless otherwise specified

Symbol	Parameter		Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage		-30	V
I_s	Diode continuous forward current	$T_c=25\text{ }^\circ\text{C}$	-50	A
I_D	Continuous drain current @ $V_{GS}=-10\text{V}$	$T_c=25\text{ }^\circ\text{C}$	-50	A
		$T_c=100\text{ }^\circ\text{C}$	-32	A
I_{DM}	Pulse drain current tested ①	$T_c=25\text{ }^\circ\text{C}$	-200	A
EAS	Avalanche energy, single pulsed ②		56	mJ
P_d	Maximum power dissipation	$T_c=25\text{ }^\circ\text{C}$	40	W
V_{GS}	Gate-Source voltage		± 20	V
$T_{STG} T_J$	Storage and operating temperature range		-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta JC}$	Thermal Resistance-Junction to Case	3.1	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	30	$^\circ\text{C/W}$

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-30	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current($T_c=25^\circ\text{C}$)	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}$	--	--	-1	μA
	Zero Gate Voltage Drain Current($T_c=125^\circ\text{C}$)	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}$	--	--	-100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.3	-1.8	-2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ③	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-20\text{A}$	--	8.8	11	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ③	$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-15\text{A}$	--	16	20	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{\text{DS}}=-15\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	3000	3305	3600	pF
C_{oss}	Output Capacitance		350	395	450	pF
C_{rss}	Reverse Transfer Capacitance		220	260	300	pF
R_g	Gate Resistance	f=1MHz	--	3.2	--	Ω
Q_g	Total Gate Charge	$V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-20\text{A}, V_{\text{GS}}=-10\text{V}$	--	59	--	nC
Q_{qs}	Gate-Source Charge		--	11	--	nC
Q_{qd}	Gate-Drain Charge		--	12	--	nC
Switching Characteristics						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=-15\text{V}, I_{\text{D}}=-20\text{A}, R_{\text{G}}=3\Omega, V_{\text{GS}}=-10\text{V}$	--	9.5	--	nS
t_r	Turn-on Rise Time		--	12	--	nS
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	51	--	nS
t_f	Turn-Off Fall Time		--	15	--	nS
Source- Drain Diode Characteristics@ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
V_{SD}	Forward on voltage	$I_{\text{SD}}=-20\text{A}, V_{\text{GS}}=0\text{V}$	--	-0.9	-1.2	V
t_{rr}	Reverse Recovery Time	$T_J=25^\circ\text{C}, I_{\text{SD}}=-20\text{A}, V_{\text{GS}}=0\text{V}$ $dI/dt=-500\text{A}/\mu\text{s}$	--	14	--	nS
Q_{rr}	Reverse Recovery Charge			22		nC

NOTE:

① Repetitive rating; pulse width limited by max. junction temperature.

② Limited by $T_{J\text{max}}$, starting $T_J = 25^\circ\text{C}$, $L = 0.5\text{mH}$, $R_G = 25\Omega$, $I_{AS} = -15\text{A}$, $V_{GS} = -10\text{V}$. Part not recommended for use above this value

③ Pulse width $\leq 300\mu\text{s}$; duty cycles $\leq 2\%$.



Vanguard
Semiconductor

VS3508AP

-30V/-50A P-Channel Advanced Power MOSFET

Typical Characteristics

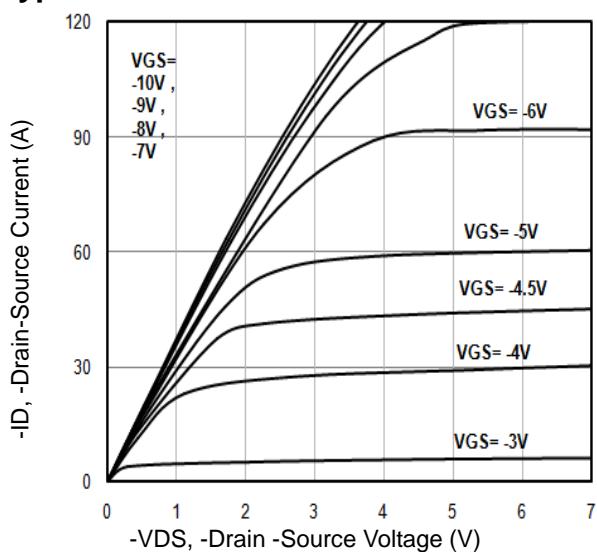


Fig1. Typical Output Characteristics

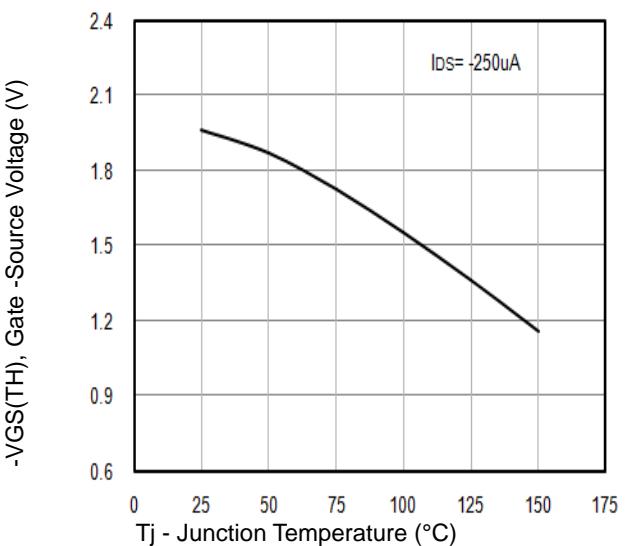


Fig2. $-VGS(TH)$ Gate -Source Voltage Vs. T_j

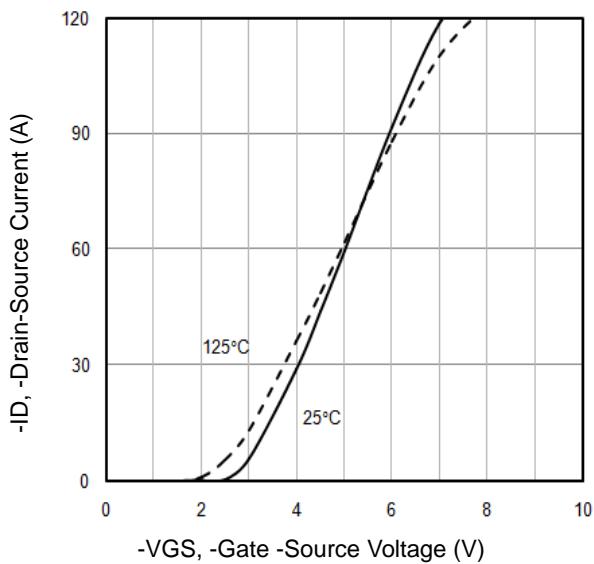


Fig3. Typical Transfer Characteristics

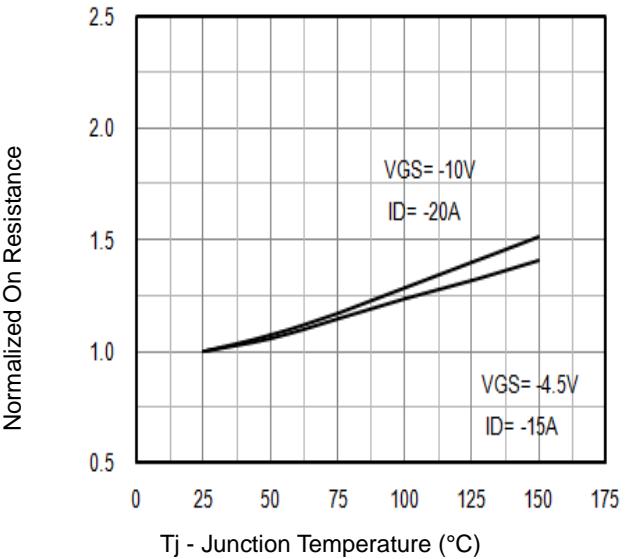


Fig4. Normalized On-Resistance Vs. T_j

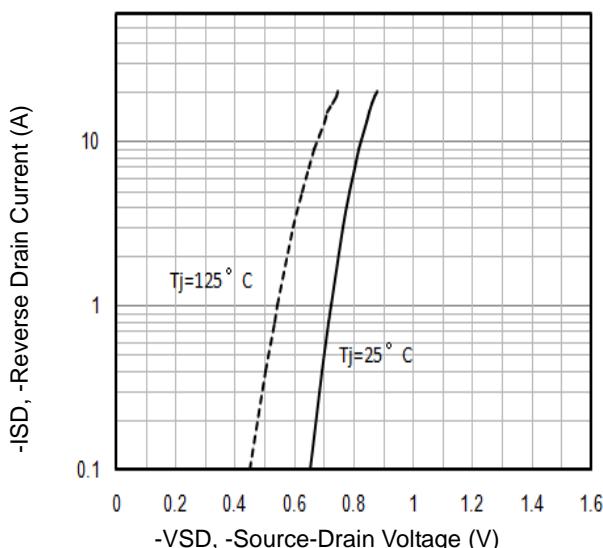


Fig5. Typical Source-Drain Diode Forward Voltage

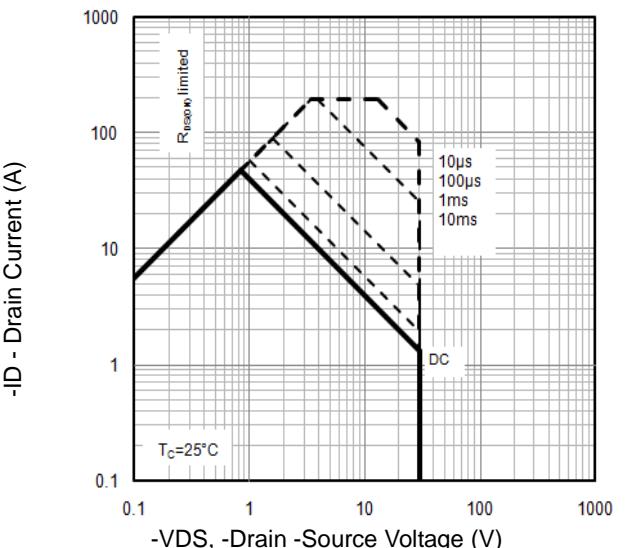


Fig6. Maximum Safe Operating Area

Typical Characteristics

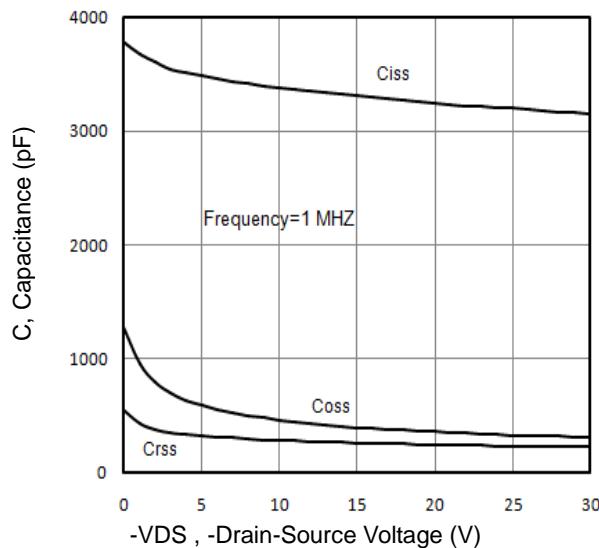


Fig7. Typical Capacitance Vs.Drain-Source Voltage

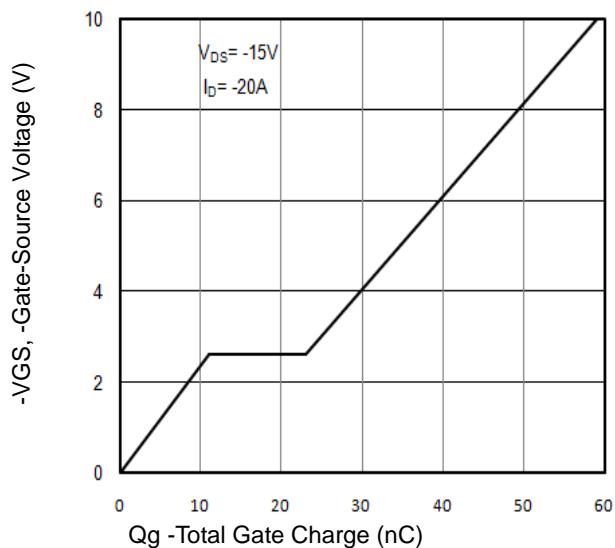


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

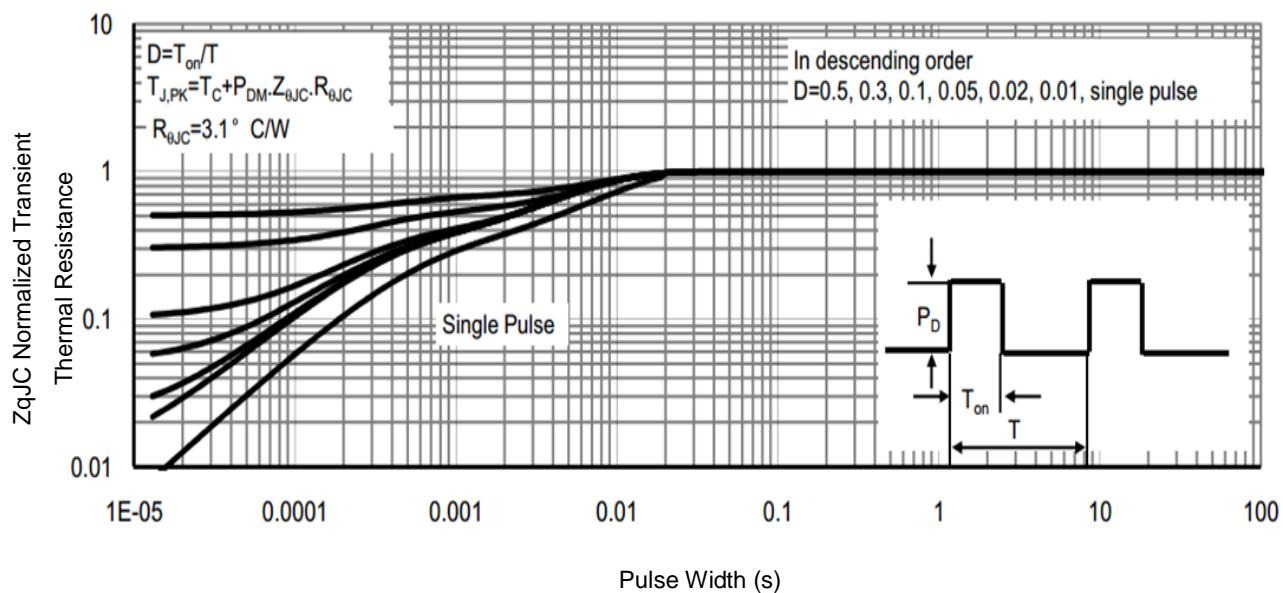


Fig9. Normalized Maximum Transient Thermal Impedance

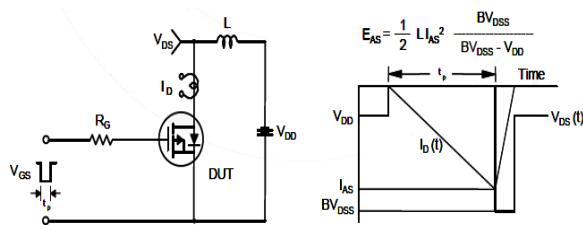


Fig10. Unclamped Inductive Test Circuit and Waveforms

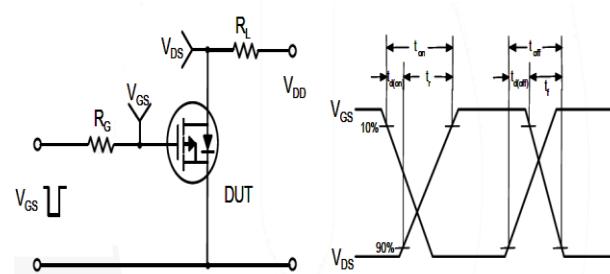
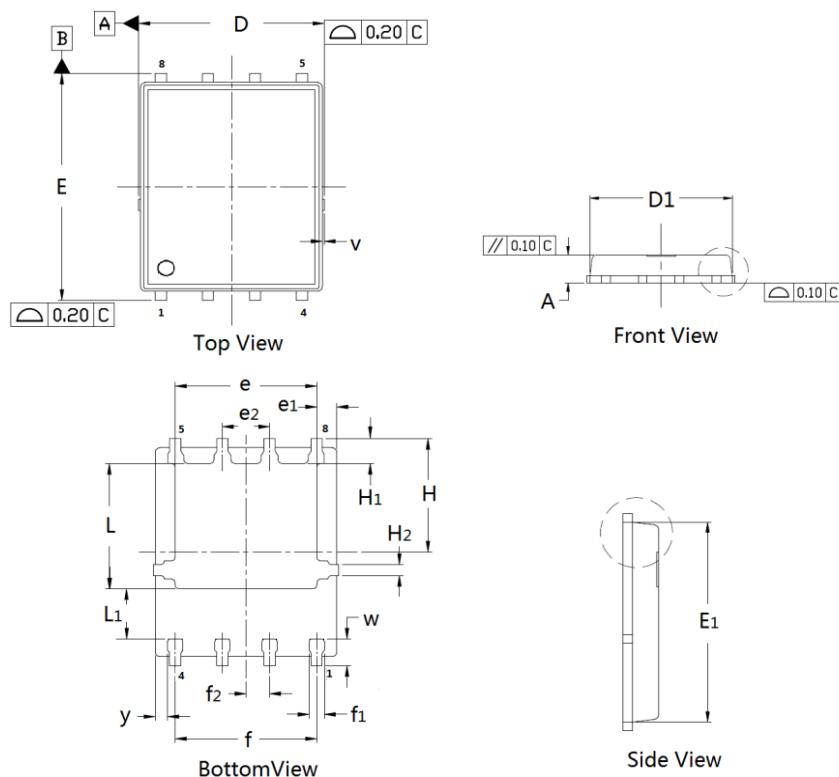


Fig11. Switching Time Test Circuit and waveforms

PDFN5×6 Package Outline Data



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.02	1.10	D	4.90	4.98	5.10
D ₁	4.80	4.89	5.00	E	6.00	6.11	6.20
E ₁	5.65	5.74	5.85	e	3.72	3.80	3.92
e ₁	--	0.54	--	e ₂	--	1.27	--
f	--	3.82	--	f ₁	0.31	0.37	0.51
f ₂	--	0.64	--	H	--	3.15	--
H ₁	0.59	0.63	0.79	H ₂	0.26	0.28	0.32
L	3.38	3.45	3.58	L ₁	--	1.39	--
V	--	0.13	--	w	0.64	0.68	0.84
y	--	0.34	--		--	--	--

Customer Service

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